

B1

$$\begin{array}{ccccccc} \text{H} & \text{H} & \text{H} & \text{H} & \text{H} & \text{H} & \text{H} \\ | & | & | & | & | & | & | \\ \text{C}_1 & \text{C}_2 & \text{C}_3 & \text{C}_4 & \text{C}_5 & \text{C}_6 & \text{C}_7 \\ | & | & | & | & | & | & | \\ \text{H} & \text{H} & \text{H} & \text{H} & \text{H} & \text{H} & \text{H} \end{array}$$

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body;

baking the laminated body; and
completing the multi-layer ceramic electronic
part.

9. (New) The method of Claim 7, additionally comprising the step of forming the ceramic portions of the external electrodes so that they are continuous from an inner surface of the conductor film of the external electrodes, where (it) closely contacts with a surface of the laminated body, up to an outer surface thereof.

10. (New) The method of Claim 7, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.